

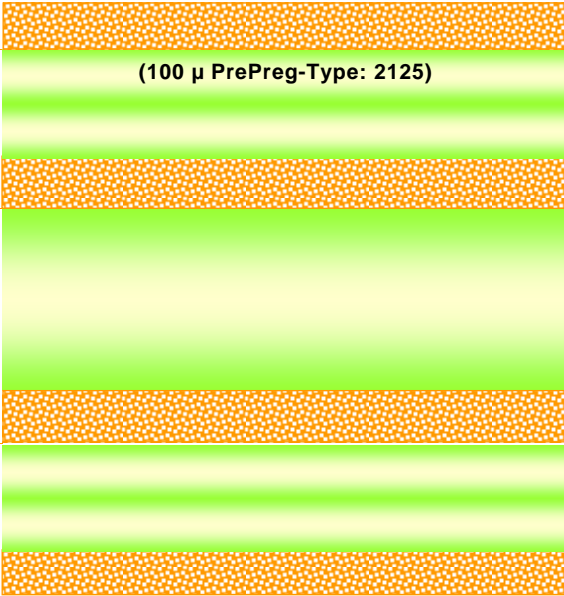
**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 204 FR4 35 L150.35 P10**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_204\_FR4\_35\_L150.35\_p10**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	35 $\mu$	Copper		<b>A1</b> <b>B</b>	
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)
	100 $\mu$	Prepreg			
<b>Layer-2</b>	35 $\mu$	Copper			
	1500 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-99</b>	35 $\mu$	Copper			

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